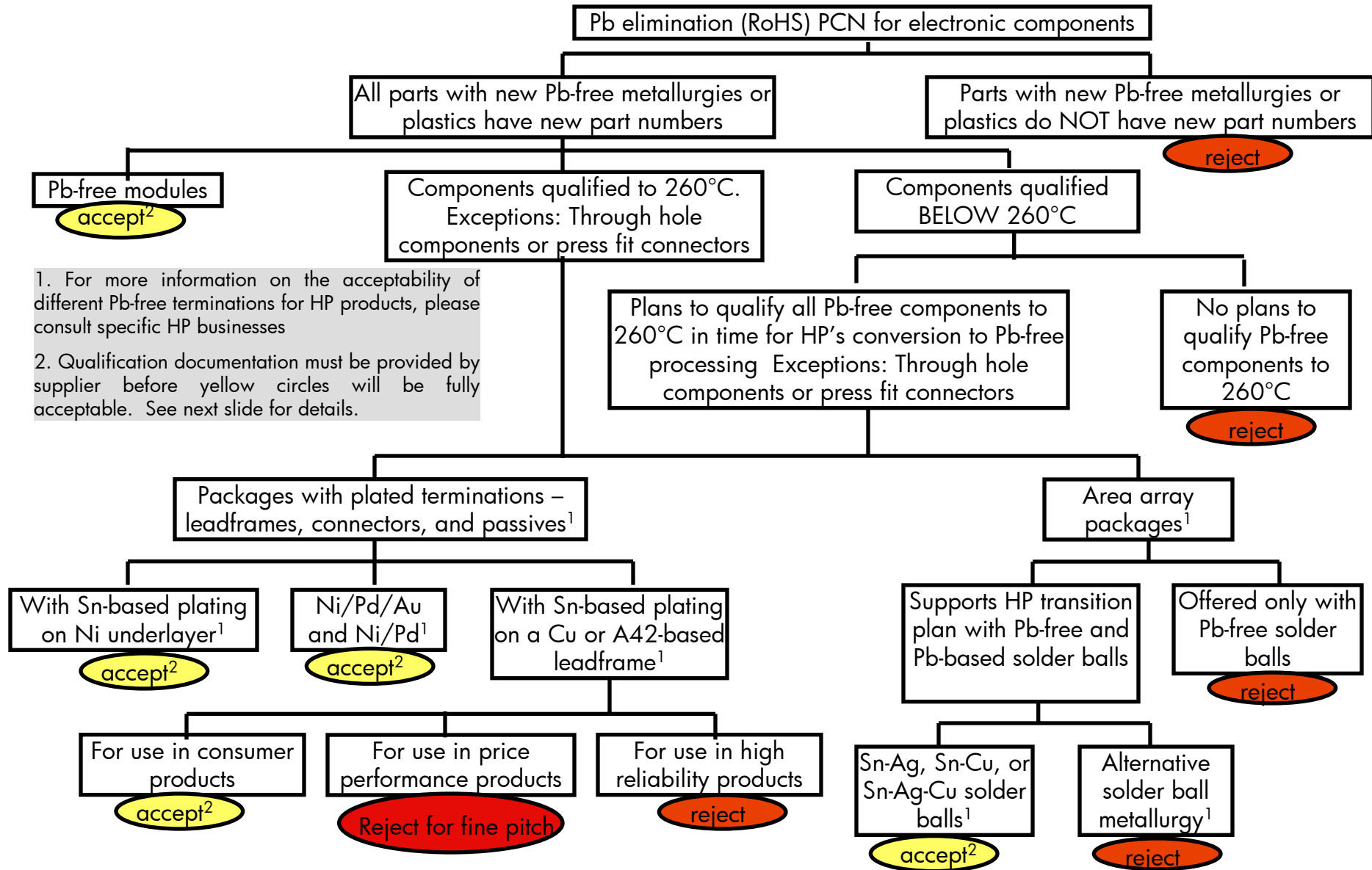


PCN response flow chart for RoHS compliance



August 2003

An example of HP's Pb-free PCN accept/reject process flow for electronic components



HP's Pb-free component qualification requirements



Qualification documentation must be provided by supplier before yellow circles will be fully acceptable

- Follow current guidelines, such as the General Semiconductor Specification, General Interconnect Specification or other specification provided by HP or its subcontractors with three additions.
 - Qualification temperatures or preconditioning to simulate second level surface mount assembly should be 260°C for surface mount devices. Follow the same guidelines for time at peak temperature or number of reflows given in existing standards or specifications.
 - Moisture sensitivity level should be determined for a 260°C peak temperature for surface mount devices
 - Tin whisker evaluations are needed for parts with a tin-based plating (provided as a separate attachment)
- HP is working to optimize test specifications for Pb-free components



i n v e n t